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SEMICONDUCTOR CHIP PACKAGING STRUCTURE

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[There are no amendments to this patent.]

Claim

Semiconductor chip packaging structure wherein part of a group of electrodes formed on one surface of a first semiconductor chip is directly connected electrically and mechanically to a pad formed on a surface near one end of a circuit board, with the rest of the electrodes on this first semiconductor chip projecting beyond the aforementioned end relative to the aforementioned circuit board and an electrode formed on a second semiconductor chip being directly connected electrically and mechanically to the rest of the electrodes.

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